

FULL ADDITIVE PROCESS WITH FILLED PLATED THROUGH HOLES

ABSTRACT

5 A method provides for additive plating on a subcomposite  
having filled plated through holes. Fine-line circuitry is  
achieved via electroless deposition onto a dielectric substrate  
after the through hole is plated and filled. Fine-line circuitry  
may be routed over landless, plated through holes thereby  
increasing the aspect ratio and the available surface area for  
10 additional components and wiring.

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